

# SP115703CLC :Part Detail

[General Information](#) | [Package Information](#) | [Environmental and Compliance Information](#) | [Manufacturing Information](#) | [Ordering Information](#) | [Product/Process Change Notice \(PCN\)](#) | [Operating Characteristics](#) | [Reliability Data Lookup](#)

## General Information

Part Number	SP115703CLC
Description	POWER MANAGEMENT 9S08QE8
Product Line	GCGZQE8
PTI	MDTE
Material Type	Tested Packaged Device
<a href="#">Life Cycle Description (code)</a>	PRODUCT STABLE GROWTH/MATURITY
Status	Active
<a href="#">Application/Qualification Tier</a>	10-YEARS APPLICATION LIFE

## Package Information

Package Type and Termination Count	QFP 32
Package Description and Mechanical Drawing	<a href="#">LQFP 32 7*7*1.4P0.8</a>
Device Weight(g)	0.18860
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	7.000
Package Width (nominal)(mm)	7.000
Package Thickness (nominal)(mm)	1.600
Maximum Height Above Board(mm)	1.600
Tape & Reel	No

## Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	<a href="#">Download MCD Report</a> <a href="#">Download MCD Report</a>
RoHS Certificate of Analysis (CoA)	<a href="#">Download RoHS CoA Report</a>

Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	<a href="#">NXP REACH Statement</a>
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

## Manufacturing Information

Micron Size(μm)	.25
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## Ordering Information

Minimum Package Quantity (MPQ)	1250
MPQ Container	BRICK
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	1250
POQ Container	BOX
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
<a href="#">Budgetary Price excluding tax(US Currency)</a>	-

Order

## Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
15684	Product Change Notice	<a href="#">POLYIMIDE REMOVAL FOR CHD 0.25SGF PRODUCTS</a>	09 Jul 2013	11 Dec 2013
15302	Product Change Notice	<a href="#">TJN 7X7 LQFP CU WIRE QUAL</a>	16 Aug 2012	14 Nov 2012
14930	Product Bulletin	<a href="#">KES-CHINA TEST BACK END EXPANSION</a>	20 Feb 2012	21 Feb 2012
14301A	Update Notification	<a href="#">9S08SE8/SH32/JS16/QB8/QE128/KA8/GT1A/QE32/SF4/SH8/AC/AW16 HC908QY4/JL8/MR8/JW16/JL3E KES-CHINA FINAL TEST SITE EXPANSION</a>	08 Dec 2010	14 Dec 2010
14315	Product Change	<a href="#">Q508QF8 NEW MASKSET 8M40J DESIGN FIX</a>	14 Sep 2010	30 Jun 2011

14301	Notice Product Bulletin	<a href="#">9S08SE8/SH32/JS16/QB8/QE128/KA8/GT1A/QE32/SF4/SH8/AC/AW16</a> <a href="#">HC908QY4/JL8/MR8/JW16/JL3E KES-CHINA Final Test site Expansion</a>	02 Sep 201003 Sep 2010
14263	Product Change Notice	<a href="#">20um Au wire qualification for SOIC28/LQFP/QFP packages in FSL-TJN-FM Assembly Site</a>	04 Aug 201002 Nov 2010

## Operating Characteristics

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Sample Exception Availability N

[Reliability Data Lookup](#)

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